

ABSTRACT

In conventional semiconductor devices, customarily, it is sought to position the mounting region of a semiconductor element in the center of a package, and hence the dimensions of the package are increased unnecessarily, but the object of the present invention is to avoid unnecessary increasing of the package dimensions, without impairing the required functions of the semiconductor device. Unnecessary increasing of package dimensions is avoided by providing a semiconductor device comprising a package having a semiconductor element mounting region, a first region containing the aforementioned mounting region, and a second region partially adjoining the periphery of the above-described first region.

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